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TFT | OLED | GRAPHIC | CHARACTER | UWVD | SEGMENT | CUSTOM

Graphic OLED Module

Part Number O25664B-GGS-TS3

Overview:

- 256x64 Graphic OLED
- White Grayscale Pixel Color
- Overall Size: 88.00mm x 27.80mm
- Parallel & Serial Interfaces

- -40C to 70C Operating Temperature
- 2.8V
- Controller: SSD1322
- RoHS Compliant



Graphic OLED Features:

Resolution: 256 x 64

Interface: 8-bit Parallel, 3/4-wire SPI

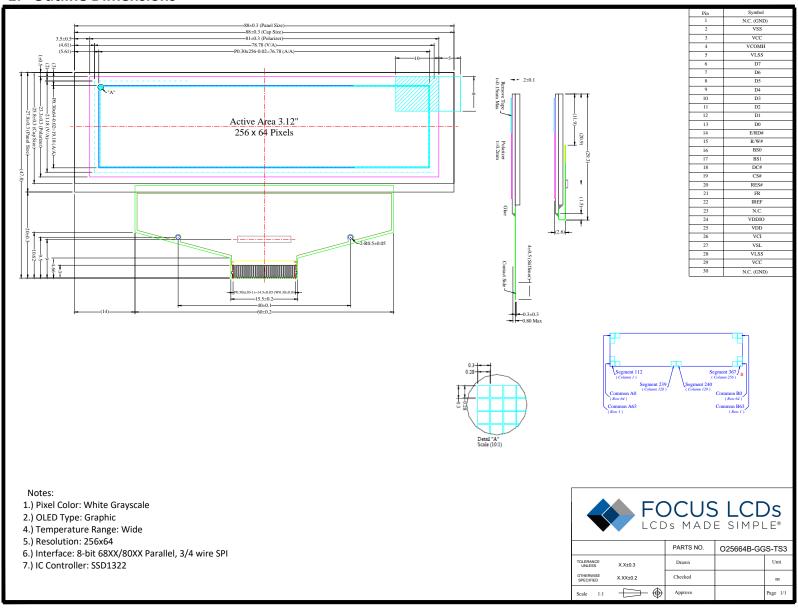
Controller: SSD1322 RoHS Compliant

General Information Items	Specification Main Panel	Unit	Note
Viewing Area	78.78 x 21.18	mm	-
Pixel Color	Grayscale	-	-
Viewing Direction	Full	-	-
Voltage	2.8	V	-
Resolution	256x64	-	-
Controller IC	SSD1322	-	-
Interface	Parallel and Serial	-	-
Operating temperature	-40 ~ +70	°C	-
Storage temperature	-40 ~ +85	°C	-

Mechanical Information

	Item	Min	Тур.	Max	Unit	Note
N 4 a alvula	X (Width)	-	88.00	-	mm	-
Module size	Y (Height)	-	27.80	1	mm	-
0.20	Z (Depth)	-	-	2.00	mm	-

1. Outline Dimensions





2. Input Terminal Pin Assignment

Recommended Connector: Hirose Part # FH19C-30S-0.5SH(10), 30 pin, 0.5mm pitch

NO.	Symbol	Description				
1	N.C.	No (Connection / Reserved	Pin		
2	VSS	(Ground of Logic Circuit			
3	VCC	Po	wer Supply for OEL Par	nel		
4	VCOMH	Voltage O	utput High Level for Co	OM Signal		
5	VLSS	(Ground of Logic Circuit			
6-13	D7-D0	Но	st Data Input/Output E	Bus		
14	E/RD#	Re	ad/Write Enable or Re	ad		
15	R/W#	Re	ad/Write Select or Wri	te		
			BS0	BS1		
16	BS0	3-Wire Serial	1	0		
		4-Wire Serial	0	0		
		8-bit 68xx Parallel	1	1		
17	BS1	8-bit 80xx Parallel	0	1		
18	D/C#	С	Data/Command Contro	I		
19	CS#		Chip Select			
20	RES#	Power F	Reset for Controller and	d Driver		
21	FR	Frame	Frequency Triggering	Signal		
22	IREF	Current Ref	erence for Brightness A	Adjustment		
23	N.C.		Reserved Pin			
24	VDDIO	Power Supply for I/O Pin				
25	VDD	Power Supply for Core Logic Circuit				
26	VCI	Po	wer Supply for Operati	on		
27	VSL	Voltage Output Low Level for SEG Signal				
28	VLSS	Ground of Analog Circuit				
29	VCC	Po	wer Supply for OEL Par	nel		
30	N.C	Res	erved Pin (Supporting	Pin)		



3. Optical Characteristics

Characteristic	Symbol	Condition	Min	Тур.	Max	Unit
Brightness	L _{br}	$V_{CI} = 2.8V$ $V_{CC} = 12.0V$	60	80	-	cd/m²
CIE (White)	X Y	-	0.25 0.27	0.29 0.31	0.33 0.35	-
Dark Room Contrast	CR	-	-	>10000:1	-	-
Viewing Angle	-	-	-	Full	-	degrees

4. DC Electrical Characteristics

Characteristics	Symbol	Conditions	Min	Тур.	Max	Unit
Supply Voltage for Operation	V _{CI}	-	2.4	2.8	3.5	V
Supply Voltage for Logic	V_{DD}	-	2.4	2.5	2.6	V
Supply Voltage for I/O Pins	V_{DDIO}	-	1.65	1.8	V _{CI}	V
Supply Voltage for Display	V _{cc}	-	11.5	12.0	12.5	V
High Level Input	V _{IH}	-	0.8V _{DDIO}	-	V_{DDIO}	V
Low Level Input	V _{IL}	-	0	-	0.2V _{DDIO}	V
High Level Output	V _{OH}	I _{out} =100μA	0.9V _{DDIO}	-	V_{DDIO}	V
Low Level Output	V _{OL}	I _{out} =100μA	0	-	0.1V _{DDIO}	V
Operating Current for V _{CI}	I _{CI}	-	-	180	300	μΑ
Operating Current for V _{CC}	I _{cc}	-	-	47.7	59.7	mA
Sleep Mode Current for V _{CI}	I _{CI, SLEEP}	-	-	20	100	μΑ
Sleep Mode Current for V _{CC}	I _{CC, SLEEP}	-	-	2	10	μА

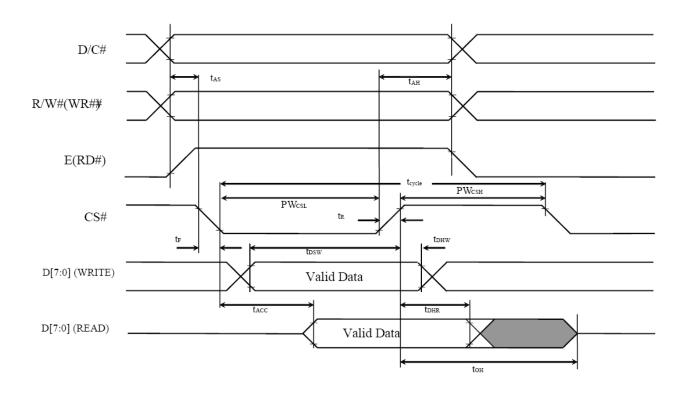
NOTE: If the maximum rating of the above parameters is exceeded, even momentarily, the quality of the product may be degraded. The maximum ratings specify the values which the product may be physically damaged if exceeded. Be sure to use the product within the range of the specified parameters.



5. Timing Characteristics

5.1 68XX-Series MPU Parallel Interface Timing Characteristics

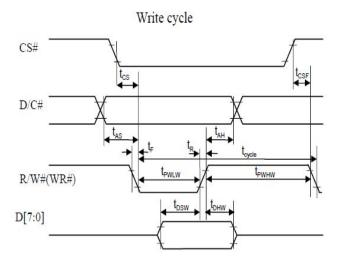
Parameter	Symbol	Min	Max	Unit
Clock Cycle Time	t _{cycle}	300	-	ns
Address Setup Time	t _{AS}	10	-	ns
Address Hold Time	t _{AH}	0	-	ns
Write Data Setup Time	t _{DSW}	40	-	ns
Write Data Hold Time	t _{DHW}	7	-	ns
Read Data Hold Time	t _{DHR}	20	-	ns
Output Disable Time	t _{он}	-	70	ns
Access Time	t _{ACC}	-	140	ns
Chip Select Low Pulse Width (Read)	PW _{CSL}	120		ns
Chip Select Low Pulse Width (Write)	PVVCSL	60	-	ns
Chip Select High Pulse Width (Read)	PW _{CSH}	60		ns
Chip Select High Pulse Width (Write)	F VV CSH	60	-	ns
Rise Time	t _r	-	15	ns
Fall Time	t _f	-	15	ns

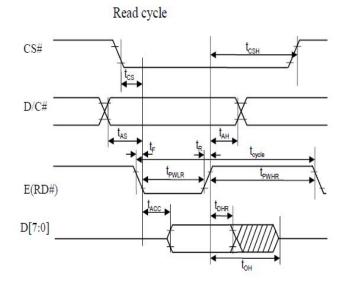




5.2 80XX-Series MPU Parallel Interface Timing Characteristics

Parameter	Symbol	Min	Max	Unit
Clock Cycle Time	t _{cycle}	300	-	ns
Address Setup Time	t _{AS}	10	-	ns
Address Hold Time	t _{AH}	0	-	ns
Write Data Setup Time	t _{DSW}	40	-	ns
Write Data Hold Time	t _{DHW}	7	-	ns
Read Data Hold Time	t _{DHR}	20	-	ns
Output Disable Time	t _{он}	-	70	ns
Access Time	t _{ACC}	-	140	ns
Read Low Time	t _{PWLR}	150	-	ns
Write Low Time	t _{PWLW}	60	-	ns
Read High Time	t _{PWHR}	60	-	ns
Write High Time	t _{PWHW}	60	-	ns
Chip Select Setup Time	t _{cs}	0	-	ns
Chip Select Hold Time to Read Signal	t _{CSH}	0	-	ns
Chip Select Hold Time	t _{CSF}	20	-	ns
Rise Time	t _r	-	15	ns
Fall Time	t _f	-	15	ns

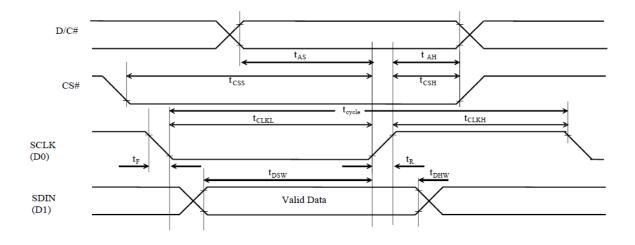


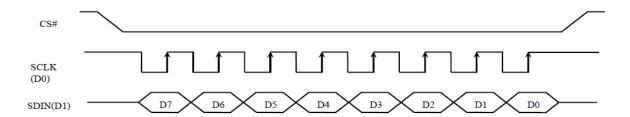




5.3 Serial Interface Timing Characteristics (4 wire Serial)

Parameter	Symbol	Min	Max	Unit
Clock Cycle Time	t _{cycle}	100	-	ns
Address Setup Time	t _{AS}	15	-	ns
Address Hold Time	t _{AH}	15	-	ns
Chip Select Setup Time	t _{CSS}	20	-	ns
Chip Select Hold Time	t _{CSH}	10	-	ns
Write Data Setup Time	t _{DSW}	15	-	ns
Write Data Hold Time	t _{DHW}	15	-	ns
Clock Low Time	t _{CLKL}	20	-	ns
Clock High Time	t _{CLKH}	20	-	ns
Rise Time	t _r	-	15	ns
Fall Time	t _f	-	15	ns

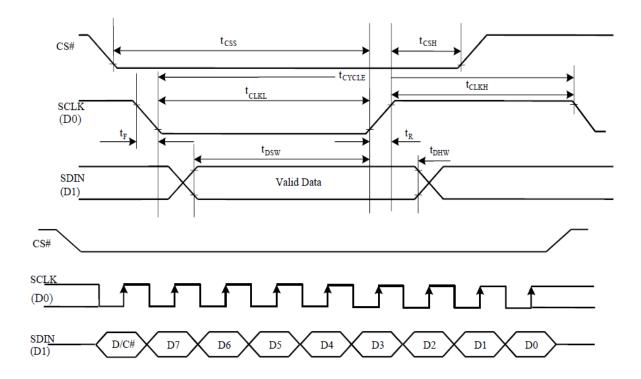






5.4 Serial Interface Timing Characteristics (3 wire Serial)

Parameter	Symbol	Min	Max	Unit
Clock Cycle Time	t _{cycle}	100	-	ns
Chip Select Setup Time	t _{CSS}	20	-	ns
Chip Select Hold Time	t _{CSH}	10	-	ns
Write Data Setup Time	t _{DSW}	15	-	ns
Write Data Hold Time	t _{DHW}	15	-	ns
Clock Low Time	t _{CLKL}	20	-	ns
Clock High Time	t _{CLKH}	20	-	ns
Rise Time	t _R	-	15	ns
Fall Time	t _F	-	15	ns





6. Cautions and Handling Precautions

6.1 Handling and Operating the Module

- 1. When the module is assembled, it should be attached to the system firmly. Do not warp or twist the module during assembly work.
- 2. Protect the module from physical shock or any force. In addition to damage, this may cause improper operation or damage to the module and back-light unit.
- 3. Note that polarizer is very fragile and could be easily damaged. Do not press or scratch the surface.
- 4. Do not allow drops of water or chemicals to remain on the display surface. If you have the droplets for a long time, staining and discoloration may occur.
- 5. If the surface of the polarizer is dirty, clean it using some absorbent cotton or softcloth.
- 6. The desirable cleaners are water, IPA (Isopropyl Alcohol) or Hexane. Do not use ketene type materials (ex. Acetone), Ethyl alcohol, Toluene, Ethyl acid or Methyl chloride. It might permanent damage to the polarizer due to chemical reaction.
- 7. If the liquid crystal material leaks from the panel, it should be kept away from the eyes or mouth. In case of contact with hands, legs, or clothes, it must be washed away thoroughly with soap.
- 8. Protect the module from static, it may cause damage to the CMOS ICs.
- 9. Use finger-stalls with soft gloves in order to keep display clean during the incoming inspection and assembly process.
- 10. Do not disassemble the module.
- 11. Protection film for polarizer on the module shall be slowly peeled off just before use so that the electrostatic charge can be minimized.
- 12. Pins of I/F connector shall not be touched directly with bare hands.
- 13. Do not connect, disconnect the module in the "Power ON" condition.
- 14. Power supply should always be turned on/off by the item Power On Sequence & Power Off Sequence.

6.2 Storage and Transportation

- 1. Do not leave the panel in high temperature, and high humidity for a long time. It is highly recommended to store the module with temperature from 0 to 35 °C and relative humidity of less than 70%
- 2. Do not store the OLED module in direct sunlight.
- 3. The module shall be stored in a dark place. When storing the modules for a long time, be sure to adopt effective measures for protecting the modules from strong ultraviolet radiation, sunlight, or fluorescent light.
- 4. It is recommended that the modules should be stored under a condition where no condensation is allowed. Formation of dewdrops may cause an abnormal operation or a failure of the module. In particular, the greatest possible care should be taken to prevent any module from being operated where condensation has occurred inside.
- 5. This panel has its circuitry FPC on the bottom side and should be handled carefully in order not to be stressed.